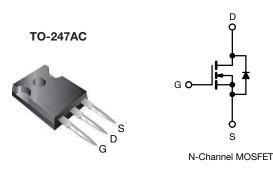
Vishay Siliconix



E Series Power MOSFET

PRODUCT SUMMA	RY			
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.156		
Q _g max. (nC)	96			
Q _{gs} (nC)	12			
Q _{gd} (nC)	25			
Configuration	Sing	le		



FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-Free and Halogen-Free	SiHG22N60AE-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	v
Gate-Source Voltage			V _{GS}	± 30	v
Continuous Drain Current (T 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	1	20	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C	ID	12	А
Pulsed Drain Current ^a			I _{DM}	49	
Linear Derating Factor				1.4	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	204	mJ
Maximum Power Dissipation			P _D	179	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope $T_J = 125 \text{ °C}$			d\//dt	70	1//22
Reverse Diode dV/dt ^d			dV/dt	31	V/ns
Soldering Recommendations (Peak temperature) ^c	For	10 s		300	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 $\Omega,$ I_{AS} = 3.8 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D, \, dI/dt$ = 100 A/µs, starting T_J = 25 °C.

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PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-		62			0000	
Maximum Junction-to-Case (Drain)	R _{thJC}	-		0.7		°C/W		
	•	·						
SPECIFICATIONS ($T_J = 25 \degree C$,	unless otherw	ise noted)						
PARAMETER	SYMBOL	-		ONS	MIN.	TYP.	MAX.	UNI
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 25	50 µA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _C	₀ = 250 μA	-	0.72	-	V/°0
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	250 μA	2	-	4	V
			$V_{GS} = \pm 20$	V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 1	μA
		V _{DS} =	= 600 V, V _{GS}	s = 0 V	-	-	1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 480 \	/, V _{GS} = 0 V	, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D	= 11 A	-	0.156	0.180	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D =	11 A	-	4.8	-	S
Dynamic						•		
Input Capacitance	C _{iss}		V _{GS} = 0 V,		-	1451	-	
Output Capacitance	C _{oss}	$V_{DS} = 100 V,$		-	73	-]	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		-	5	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}		(1		-	50	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$v_{\rm DS} = 0.0$	/ to 480 V, \	/ _{GS} = 0 V	-	258	-	
Total Gate Charge	Qg				-	48	96	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	I _D = 11 A	A, V _{DS} = 480 V	-	12	-	nC
Gate-Drain Charge	Q _{gd}				-	25	-	
Turn-On Delay Time	t _{d(on)}				-	19	38	
Rise Time	t _r	V _{PP} -	= 480 V, I _D =	- 11 A	-	33	66	
Turn-Off Delay Time	t _{d(off)}		= 10 V, R _g =		-	45	90	ns
Fall Time	t _f		Ū		-	21	42	
Gate Input Resistance	Rg	f = 1	MHz, open	drain	0.3	0.6	1.2	Ω
Drain-Source Body Diode Characterist	ics							
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol		-	-	20	
Pulsed Diode Forward Current	I _{SM}	integral revers p - n junction			-	-	49	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 11 A,	V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}				-	319	638	ns
Reverse Recovery Charge	Q _{rr}		5° C, $I_F = I_S =$		-	4.9	9.8	μC
Reverse Recovery Current	I _{RRM}	ai/at = 1	100 A/µs, V _F	q = 25 V	-	28	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

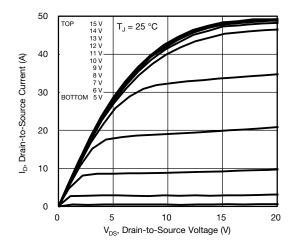


Fig. 1 - Typical Output Characteristics

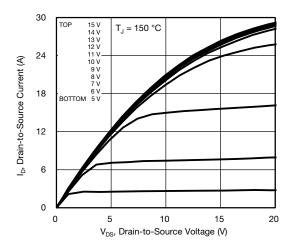
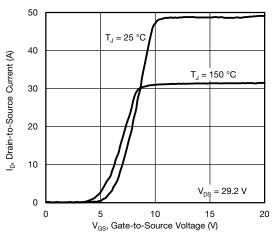


Fig. 2 - Typical Output Characteristics





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3.0 = 11 A R_{DS(on)}, Drain-to-Source On-Resistance 2.5 2.0 (Normalized) 1.5 1.0 10 \ GS 0.5 0 -20 -60 -40 20 40 60 80 100 120 140 160 0 T_J, Junction Temperature (°C)

Fig. 4 - Normalized On-Resistance vs. Temperature

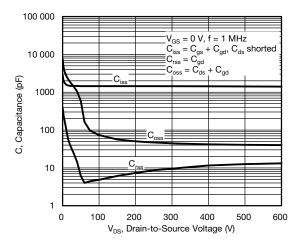


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

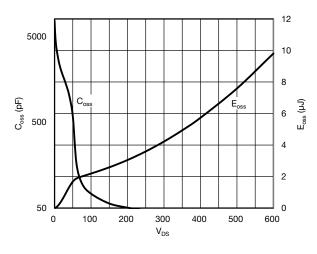


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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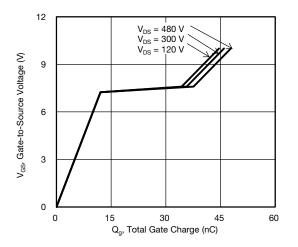


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

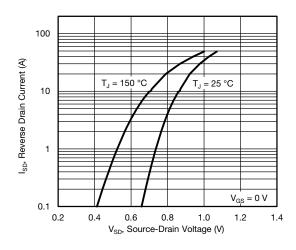


Fig. 8 - Typical Source-Drain Diode Forward Voltage

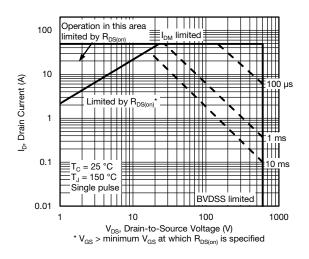


Fig. 9 - Maximum Safe Operating Area

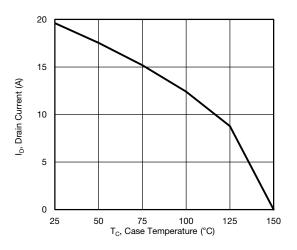


Fig. 10 - Maximum Drain Current vs. Case Temperature

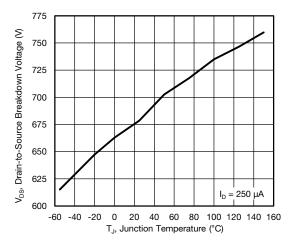
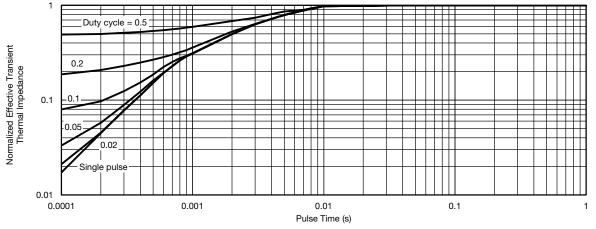


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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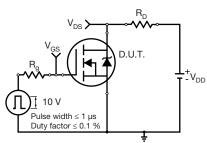


Fig. 13 - Switching Time Test Circuit

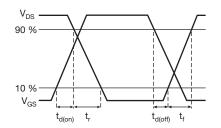


Fig. 14 - Switching Time Waveforms

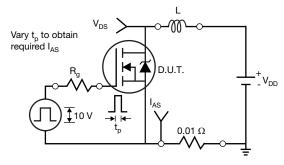


Fig. 15 - Unclamped Inductive Test Circuit

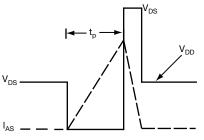


Fig. 16 - Unclamped Inductive Waveforms

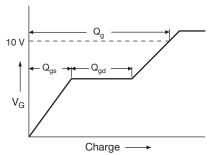


Fig. 17 - Basic Gate Charge Waveform

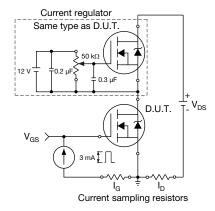


Fig. 18 - Gate Charge Test Circuit

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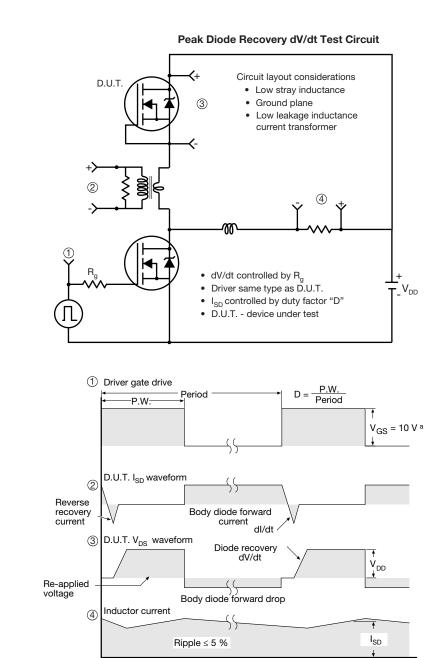


Fig. 19 - For N-Channel

Note

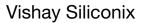
a. $V_{GS} = 5$ V for logic level devices

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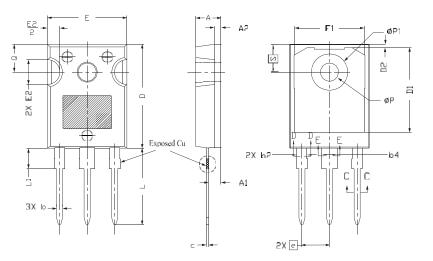
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TO-247AC (High Voltage)

VERSION 1: FACILITY CODE = 9





	М	ILLIMETERS		
DIM.	MIN.	NOM.	MAX.	NOTES
А	4.83	5.02	5.21	
A1	2.29	2.41	2.55	
A2	1.17	1.27	1.37	
b	1.12	1.20	1.33	
b1	1.12	1.20	1.28	
b2	1.91	2.00	2.39	6
b3	1.91	2.00	2.34	
b4	2.87	3.00	3.22	6, 8
b5	2.87	3.00	3.18	
С	0.40	0.50	0.60	6
c1	0.40	0.50	0.56	
D	20.40	20.55	20.70	4

		MILLIMETER	S	
DIM.	MIN.	NOM.	MAX.	NOTES
D1	16.46	16.76	17.06	5
D2	0.56	0.66	0.76	
E	15.50	15.70	15.87	4
E1	13.46	14.02	14.16	5
E2	4.52	4.91	5.49	3
е		5.46 BSC		
L	14.90	15.15	15.40	
L1	3.96	4.06	4.16	6
ØР	3.56	3.61	3.65	7
Ø P1		7.19 ref.		
Q	5.31	5.50	5.69	
S		5.51 BSC		

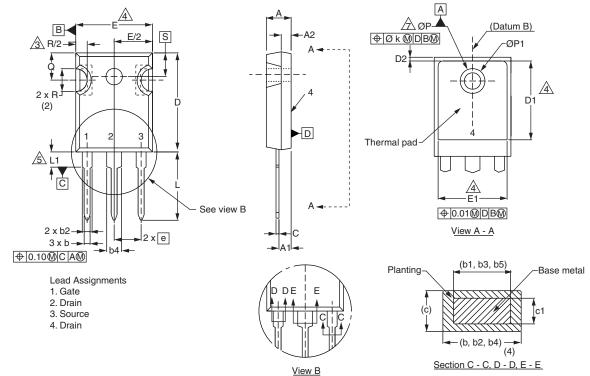
Notes

- ⁽¹⁾ Package reference: JEDEC[®] TO247, variation AC
- (2) All dimensions are in mm
- ⁽³⁾ Slot required, notch may be rounded
- ⁽⁴⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm per side. These dimensions are measured at the outermost extremes of the plastic body
- ⁽⁵⁾ Thermal pad contour optional with dimensions D1 and E1
- (6) Lead finish uncontrolled in L1
- (7) Ø P to have a maximum draft angle of 1.5° to the top of the part with a maximum hole diameter of 3.91 mm
- (8) Dimension b2 and b4 does not include dambar protrusion. Allowable dambar protrusion shall be 0.1 mm total in excess of b2 and b4 dimension at maximum material condition



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VERSION 2: FACILITY CODE = Y



	MILLIN	IETERS	
DIM.	MIN.	MAX.	NOTES
A	4.58	5.31	
A1	2.21	2.59	
A2	1.17	2.49	
b	0.99	1.40	
b1	0.99	1.35	
b2	1.53	2.39	
b3	1.65	2.37	
b4	2.42	3.43	
b5	2.59	3.38	
с	0.38	0.86	
c1	0.38	0.76	
D	19.71	20.82	
D1	13.08	-	

	MILLIN	IETERS	
DIM.	MIN.	MAX.	NOTES
D2	0.51	1.30	
E	15.29	15.87	
E1	13.72	-	
е	5.46	BSC	
Øk	0.2	254	
L	14.20	16.25	
L1	3.71	4.29	
ØР	3.51	3.66	
Ø P1	-	7.39	
Q	5.31	5.69	
R	4.52	5.49	
S	5.51	BSC	

Notes

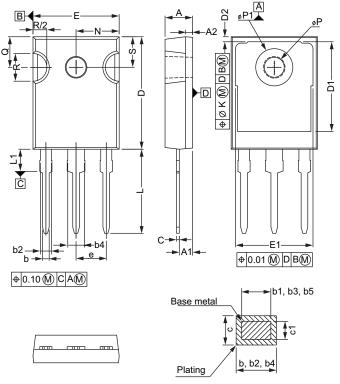
- ⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994
- ⁽²⁾ Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- ⁽⁴⁾ Thermal pad contour optional with dimensions D1 and E1
- ⁽⁵⁾ Lead finish uncontrolled in L1
- ⁽⁶⁾ Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- ⁽⁷⁾ Outline conforms to JEDEC outline TO-247 with exception of dimension c

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VERSION 3: FACILITY CODE = N



	MILLIN	IETERS		MILLIN	IETERS
DIM.	MIN.	MAX.	DIM.	MIN.	MAX
А	4.65	5.31	D2	0.51	1.35
A1	2.21	2.59	E	15.29	15.87
A2	1.17	1.37	E1	13.46	-
b	0.99	1.40	е	5.46	BSC
b1	0.99	1.35	k	0.:	254
b2	1.65	2.39	L	14.20	16.10
b3	1.65	2.34	L1	3.71	4.29
b4	2.59	3.43	N	7.62	BSC
b5	2.59	3.38	Р	3.56	3.66
С	0.38	0.89	P1	-	7.39
c1	0.38	0.84	Q	5.31	5.69
D	19.71	20.70	R	4.52	5.49
D1	13.08	-	S	5.51	BSC

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994

⁽²⁾ Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁴⁾ Thermal pad contour optional with dimensions D1 and E1

⁽⁵⁾ Lead finish uncontrolled in L1

⁽⁶⁾ Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")



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